

CLMPTO

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1. A method for fabricating semiconductor packages, comprising:  
providing a leadframe for packages that are to be singulated with respective predetermined package body sizes;  
forming individual mold caps on the leadframe with mold cap dimensions that are larger than the respective predetermined package body sizes; and  
sawing the mold caps and leadframe to singulate packages therefrom and reduce the dimensions of the mold caps to the respective predetermined package body sizes.
2. The method of claim 1 wherein providing a leadframe and forming individual mold caps thereon further comprise providing a leadframe and forming individual mold caps thereon having spacings closer together than the spacings of leadframes and mold caps for a corresponding punch singulation leadframe.
3. The method of claim 1;  
further comprising forming integral sawing guides on the mold caps; and  
wherein sawing the mold caps and leadframe further comprises sawing the mold caps and leadframe with a saw blade and utilizing the integral sawing guides to assist the saw blade.
4. The method of claim 3 wherein forming the integral sawing guides further comprises forming raised ridges on the mold caps.
5. The method of claim 3 wherein forming the integral sawing guides further comprises forming slots in the mold caps.
6. The method of claim 1 wherein forming individual mold caps on the leadframe further comprises forming mold caps by pocket molding.

7. The method of claim 1 wherein sawing the mold caps and leadframe to singulate packages therefrom further comprises sawing a tape free leadframe to singulate the packages.

8. A method for fabricating semiconductor packages, comprising:  
providing an array leadframe for packages that are to be singulated with respective predetermined package body sizes;

forming individual mold caps on the array leadframe by pocket molding the mold caps with mold cap lateral dimensions that are larger than the respective predetermined package body sizes; and  
sawing the mold caps and array leadframe to singulate packages therefrom and reduce the lateral dimensions of the mold caps to the respective predetermined package body sizes.

9. The method of claim 8 wherein providing an array leadframe and forming individual mold caps on the array leadframe further comprise providing an array leadframe and forming individual mold caps thereon having spacings closer together than the spacings of leadframes and mold caps for a corresponding punch singulation leadframe array.

10. The method of claim 8:  
further comprising forming integral sawing guides on the mold caps; and  
wherein sawing the mold caps and array leadframe further comprises sawing the mold caps and array leadframe with a saw blade and utilizing the integral sawing guides to assist the saw blade.

11. The method of claim 10 wherein forming the integral sawing guides further comprises forming raised ridges on the mold caps.

12. The method of claim 10 wherein forming the integral sawing guides further comprises forming slots in the mold caps.

13. The method of claim 8 wherein sawing the mold caps and array leadframe to singulate packages therefrom further comprises sawing a tape free leadframe to singulate the packages.

CLAIMS 14-26 (CANCELLED)